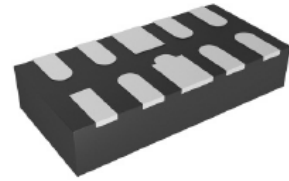


APPLICATIONS

- High Definition Multi-Media Interface(HDM).
- Digital Visual Interface(DVI).
- Unified Display interface(UDI).
- MDDI Ports.
- PCI Express.
- Serial ATA.



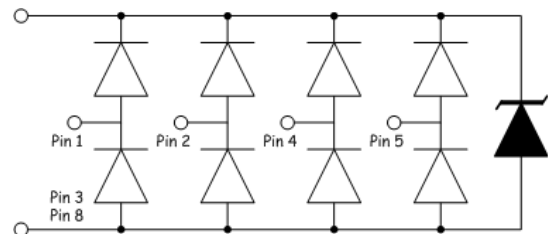
DFN2510

MECHANICAL CHARACTERISTICS

- DFN2510 Package.
- Molding Compound Flammability Rating: UL 94V-O.
- Weight 15 Milligrams (Approximate).
- Quantity per Reel: 3000pcs.
- Reel Size: 7inch.
- Lead Finish: Lead Free.

IEC COMPATIBILITY

- IEC61000-4-2(ESD) $\pm 15KV$ (air), $\pm 8KV$ (contact).
- IEC61000-4-4(EFT) 40A (5/50ns).
- IEC61000-4-5(Lightning) 2A (8/20 μ s).



PIN CONFIGURATION

FEATURES

- 100 Watts Peak Pulse Power per Line ($t_p=8/20\mu$ s).
- Protect two or four I/O lines.
- Low capacitance: 0.5pF typical (I/O to I/O)
- Low operating voltage: 5V.
- ROHS Compliant.

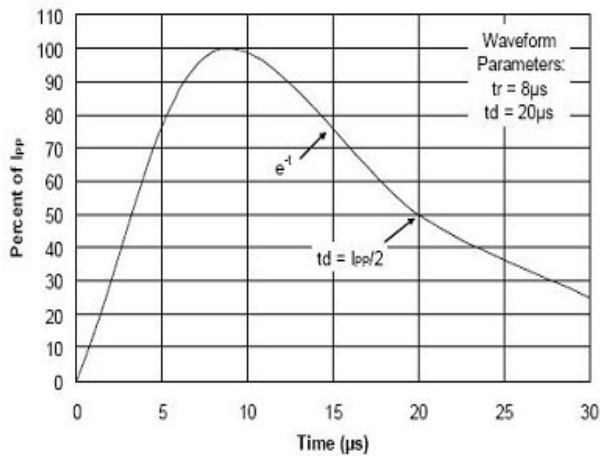
DEVICE CHARACTERISTICS

MAXIMUM RATINGS (@25°C Unless Otherwise Specified)			
PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power ($t_p=8/20\mu$ s waveform)	P_{PP}	100	Watts
Lead Soldering Temperature	T_L	260(10sec)	°C
Operating Temperature Range	T_J	-55 to +150	°C
Storage Temperature Range	T_{STG}	-55 to + 150	°C

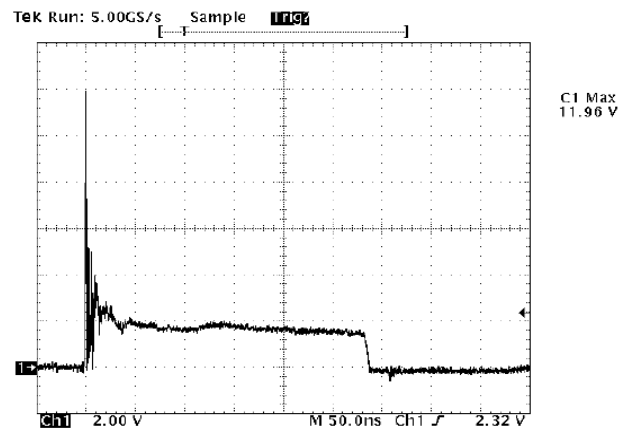
ELECTRICAL CHARACTERISTICS PER LINE (@25°C Unless Otherwise Specified)

PART NUMBER	V _{RWM} (V) (max.)	V _B (V) (min.)	I _T (mA)	V _C (V) @1A (max.)	V _C (V) (max.)(@A)	I _R (μA) (max.)	C _T (pF) (typ)	
SBC0524P	5.0	6.0	1	15	25	2	1	0.8

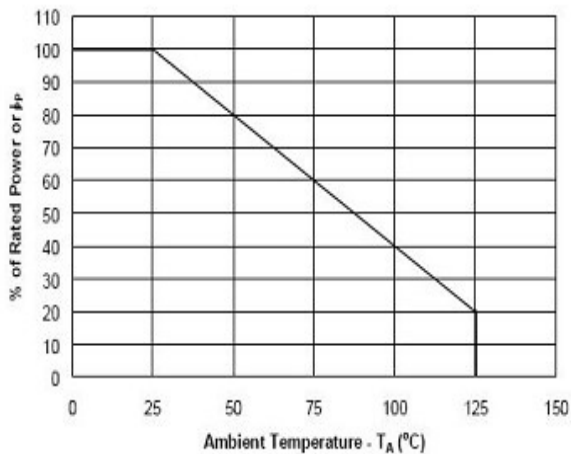
Pulse Waveform



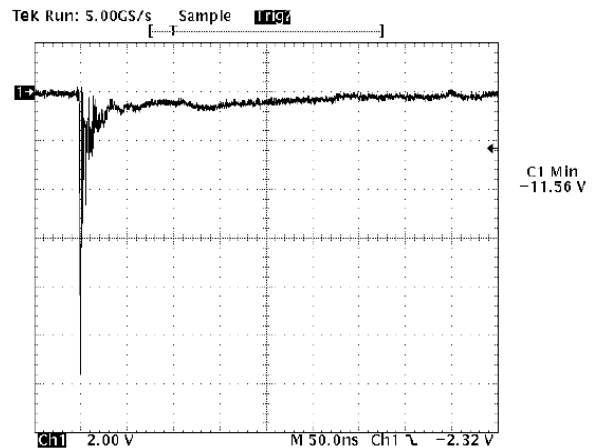
**ESD Clamping
(8kV Contact per IEC 61000-4-2)**



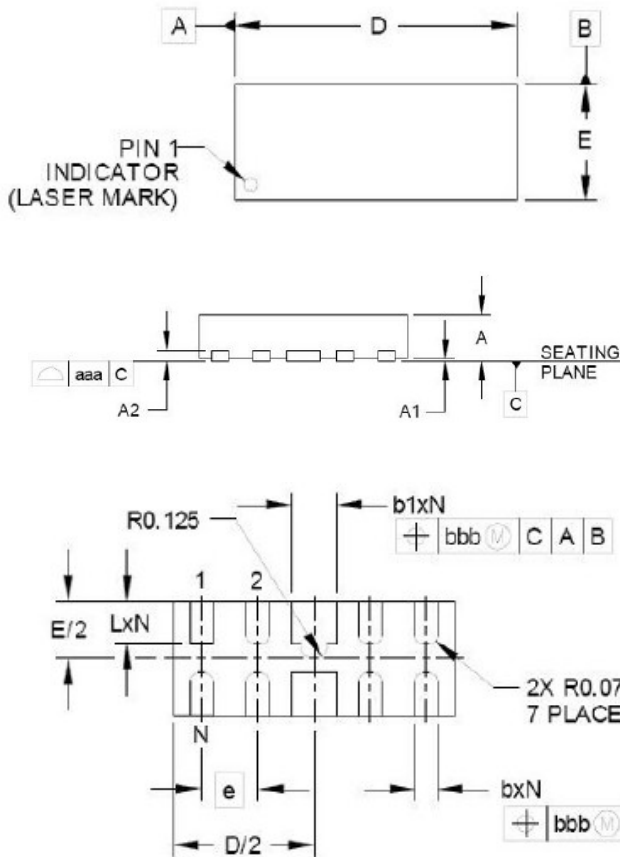
Power Derating Curve



**ESD Clamping
(-8kV Contact per IEC 61000-4-2)**

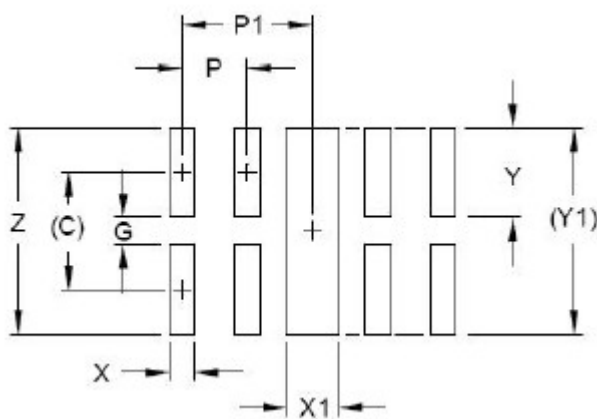


DSON-10 PACKAGE OUTLINE & DIMENSIONS



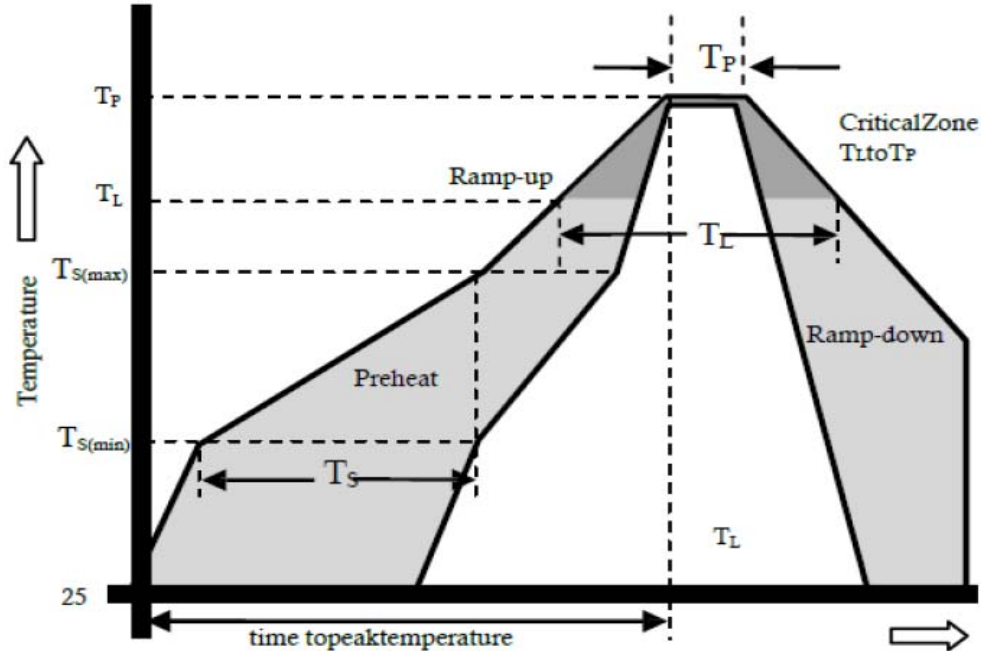
DIMENSIONS						
DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	Nom	MAX
A	.020	.023	.026	0.50	0.58	0.65
A1	0.00	.001	.002	0.00	0.03	0.05
A2	(.005)			(0.13)		
b	.006	.008	.010	0.15	0.20	0.25
b1	.014	.016	.018	0.35	0.40	0.45
D	.094	.098	.102	2.40	2.50	2.60
E	.035	.039	.043	0.90	1.00	1.10
e	.020 BSC			0.50 BSC		
L	.012	.015	.017	0.30	0.38	0.425
N	10			10		
aaa	.003			0.08		
bbb	.004			0.10		

SOLDERING FOOTPRINT



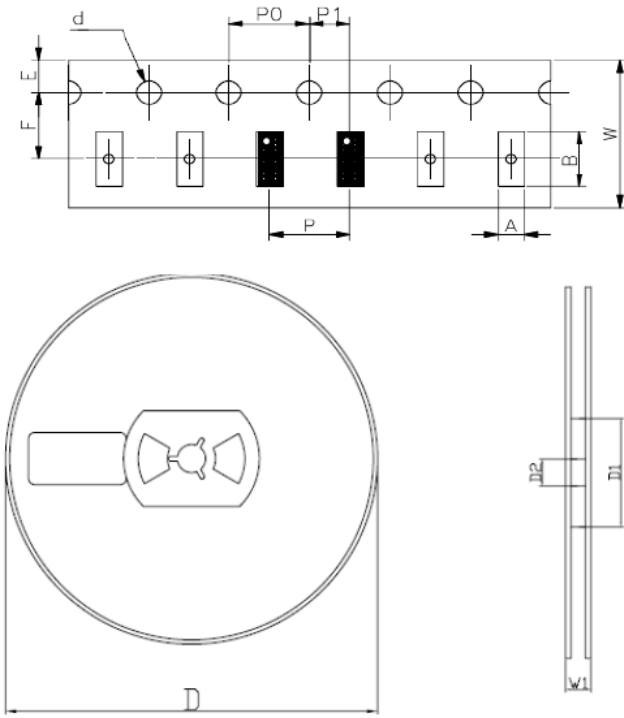
DIMENSIONS		
DIM	INCHES	MILLIMETERS
C	(.034)	(0.875)
G	.008	0.20
P	.020	0.50
P1	.039	1.00
X	.008	0.20
X1	.016	0.40
Y	.027	0.675
Y1	(.061)	(1.55)
Z	.061	1.55

REFLOW PROFILE



Reflow Condition		Pb-Free Assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time (Min to Max)	20 - 80 secs
Average ramp up rate (Liquid) Temperature (T _L) to peak		3°C/s Max.
T _S (Max) to T _L -Ramp-up Rate		3°C/s Max.
Reflow	-Temperature (T _L)(Liquid)	217°C
	-Temperature (T _L)	60 - 150 secs
Peak Temperature (T _P)		(260+0/-5)°C
Time within 5°C of actual Peak Temperature (T _P)		8- 15 secs
Ramp-down Rate		6°C/s Max.
Time 25°C to peak Temperature(T _P)		8 min Max
Do not exceed		260°C

PACKGE REEL INFORMATION



REF	mm	inch
A	1.3+/-0.1	0.051+/-0.004
B	3.0+/-0.1	0.354+/-0.004
d	1.25+/-0.1	0.049+/-0.004
D	178+/-1.0	7.01+/-0.039
D1	55+/-3	2.165+/-0.118
D2	13+/-0.5	0.512+/-0.020
E	1.75+/-0.1	0.069+/-0.004
F	3.6+/-0.2	0.138+/-0.008
P	4.0+/-0.2	0.158+/-0.008
P0	4.0+/-0.2	0.158+/-0.008
P1	2.0+/-0.2	0.079+/-0.008
W	8.0+/-0.2	0.315+/-0.008
W1	14.4+/-0.5	0.567+/-0.020

OUTLINE	Reel(PCS)
Taping	3000